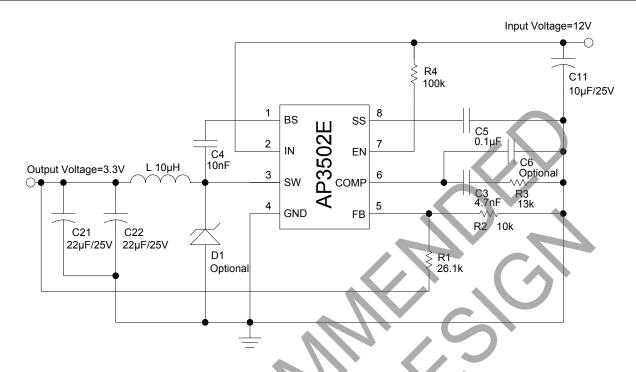


Typical Applications Circuit

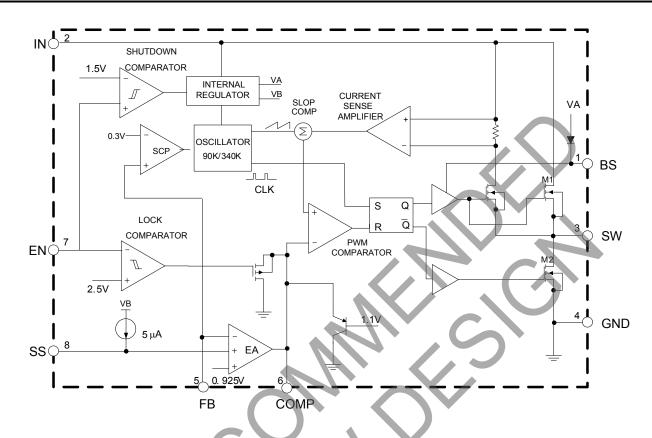


Pin Descriptions

Pin Number	Pin Name	Function
1	BS	Bootstrap pin. A bootstrap capacitor is connected between the BS pin and SW pin. The voltage across the bootstrap capacitor drives the internal high-side power MOSFET
2	IN	Supply power input pin. A capacitor should be connected between the IN pin and GND pin to keep the input voltage constant
3	SW	Power switch output pin. This pin is connected to the inductor and bootstrap capacitor
4	GND	Ground pin
5	FB	Feedback pin. This pin is connected to an external resistor divider to program the system output voltage. When the FB pin voltage exceeds 1.1V, the over voltage protection is triggered. When the FB pin voltage is below 0.3V, the oscillator frequency is lowered to realize short circuit protection
6	СОМР	Compensation pin. This pin is the output of the transconductance error amplifier and the input to the current comparator. It is used to compensate the control loop. Connect a series RC network from this pin to GND. In some cases, an additional capacitor from this pin to GND pin is required
7	EN	Control input pin. EN is a digital input that turns the regulator on or off. Drive EN high/low to turn on/off the regulator. Pull up with $100k\Omega$ resistor for automatic startup
8	SS	Soft-start control input pin. SS controls the soft-start period. Connect a capacitor from SS to GND to set the soft-start period. A 0.1µF capacitor sets the soft-start period to 15ms. To disable the soft-start feature, leave SS unconnected



Functional Block Diagram





Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Value	Unit
V _{IN}	IN Pin Voltage	-0.3 to 20	V
V _{EN}	EN Pin Voltage	-0.3 to V _{IN}	V
Vsw	SW Pin Voltage	21	V
V _{BS}	BS Pin Voltage	-0.3 to V _{SW} +6	V
V _{FB}	FB Pin Voltage	-0.3 to 6	V
V _{COMP}	COMP Pin Voltage	-0.3 to 6	V
V _{SS}	SS Pin Voltage	-0.3 to 6	V
θЈΑ	Thermal Resistance	105	°C/W
TJ	Operating Junction Temperature	+150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
T _{LEAD}	Lead Temperature (Soldering, 10s)	+260	°C
V _{HBM}	ESD (Human Body Model)	2000	V
V _{MM}	ESD (Machine Model)	200	V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods can affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Min	Мах	Unit
V _{IN}	Input Voltage	4.5	18	V
TA	Operating Ambient Temperature	-40	+85	°C



Electrical Characteristics (T_A=+25°C, V_{IN}=V_{EN}=12V, V_{OUT}=3.3V, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit		
SUPPLY VOLTAGE (IN PIN)								
V _{IN}	Input Voltage	_	4.5	_	18	V		
IQ	Quiescent Current	V _{FB} =1V, V _{EN} =3V	_	1.2	1.4	mA		
I _{SHDN}	Shutdown Supply Current	V _{EN} =0V		0.1	10	μA		
UNDER VOLT	AGE LOCKOUT							
V _{UVLO}	Input UVLO Threshold	V _{IN} Rising	3.65	4.00	4.25	V		
V _{HYS}	Input UVLO Hysteresis	_	-	200	_	mV		
ENABLE (EN	PIN)							
-	EN Shutdown Threshold Voltage	- /	1.1	1.5	2	V		
-	EN Shutdown Threshold Voltage Hysteresis (Note 3)	-	- (350	_	mV		
-	EN Lockout Threshold Voltage	AX/	2.2	2.5	2.7	V		
_	EN Lockout Hysteresis	-///		210	_	mV		
VOLTAGE RE	FERENCE (FB PIN)							
V_{FB}	Feedback Voltage	-	0.907	0.925	0.943	V		
V _{FBOV}	Feedback Over Voltage Threshold	-	_	1.1	_	V		
I _{FB}	Feedback Bias Current	V _{FB} =1V	-0.1	_	0.1	μA		
MOSFET	. ()							
R _{DSONH}	High-side Switch On-resistance (Note 2)	I _{SW} =0.2A/0.7A	_	100	_	mΩ		
R _{DSONL}	Low-side Switch On-resistance (Note 2)	I _{SW} =-0.2A/-0.7A	_	100	_	mΩ		
CURRENT LIN	CURRENT LIMIT							
I _{LEAKH}	High-side Switch Leakage Current	V _{IN} =18V,V _{EN} =V _{SW} =	_	0.1	10	μA		
I _{LIMH}	High-Side Switch Current Limit	_	2.7	3.5	_	Α		
I _{LIML}	Low-Side Switch Current Limit	Drain to Source	_	0	_	mA		
SWITCHING REGULATOR								
fosc1	Oscillator Frequency	_	280	340	400	kHz		
fosc2	Short Circuit Oscillator Frequency	_	_	90	_	kHz		
D _{MAX}	Maximum Duty Cycle	V _{FB} =0.85V	_	90	_	%		
D _{MIN}	Minimum Duty Cycle	V _{FB} =1V	_	_	0	%		



Electrical Characteristics (continued) (T_A=+25°C, V_{IN}=V_{EN}=12V, V_{OUT}=3.3V, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit		
ERROR AMP	ERROR AMPLIFIER							
A _{EA}	Error Amplifier Voltage Gain (Note 3)	_	_	400	_	V/V		
G _{EA}	Error Amplifier Transconductance	_	_	800	_	μA/V		
G _{CS}	COMP to Current Sense Transconductance	_	_	3.5	_	A/V		
THERMAL SHUTDOWN								
T _{OTSD}	Thermal Shutdown (Note 3)	_		+160	_	°C		
T _{HYS}	Thermal Shutdown Hysteresis (Note 3)	-	7	+30	_	°C		
SOFT START (SS PIN)								
t _{SS}	Soft-start Time (Note 3)	C5=0.1µF	-	15		ms		
_	Soft-start Current	- ()	- (5	_	μΑ		

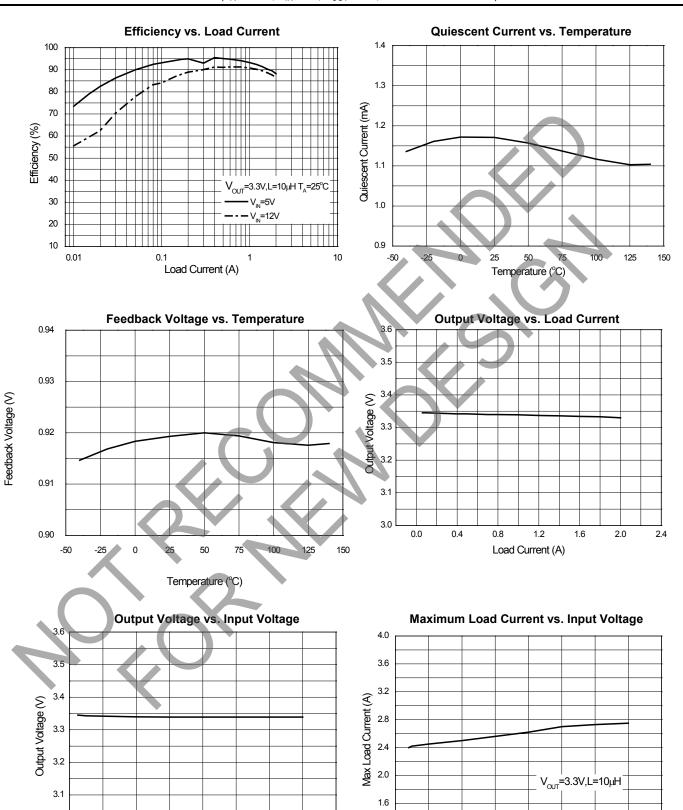
Notes: 2. $R_{DSON} = \frac{V_{SW1} - V_{SW2}}{V_{SW1}}$

Isw1 - Isw2

3. Not tested, guaranteed by design.



$\textbf{Performance Characteristics} \text{ (T_A=+25°C, V_{IN}=12V, V_{OUT}=3.3V, unless otherwise noted.)}$



Input Voltage (V)

3.0

4

20

1.2

20

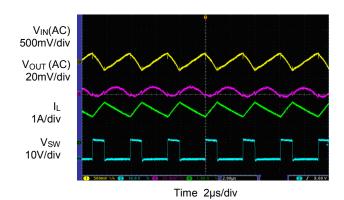
16

Input Voltage (V)

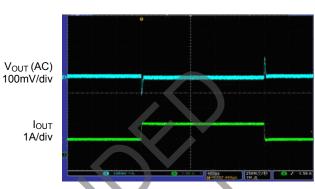


$\label{eq:continued} \textbf{Performance Characteristics} \ \ \text{(continued)} \ \ (T_A = +25^{\circ}\text{C}, \ V_{IN} = 12\text{V}, \ V_{OUT} = 3.3\text{V}, \ unless \ otherwise \ noted.)$

Output Ripple (I_{OUT}=2A)

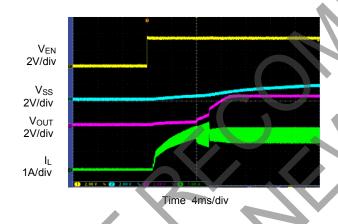


Load Transient (I_{OUT}=1A to 2A)

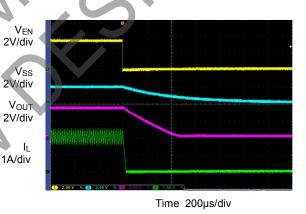


Time 400µs/div

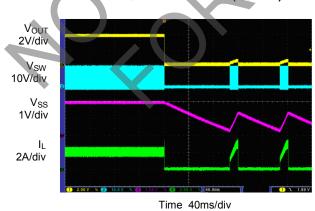
Enable Turn-on Characteristic (V_{IN}=12V, V_{EN}=3.3V, V_{OUT}=3.3V, I_{OUT}=2A)



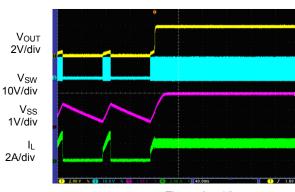
Enable Turn-off Characteristic (V_{IN}=12V, V_{EN}=3.3V, V_{OUT}=3.3V, I_{OUT}=2A)



Short Circuit Protection (IOUT=2A)



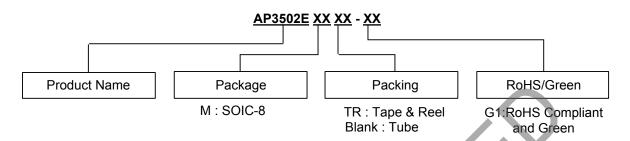
Short Circuit Recovery (I_{OUT}=2A)



Time 40ms/div



Ordering Information



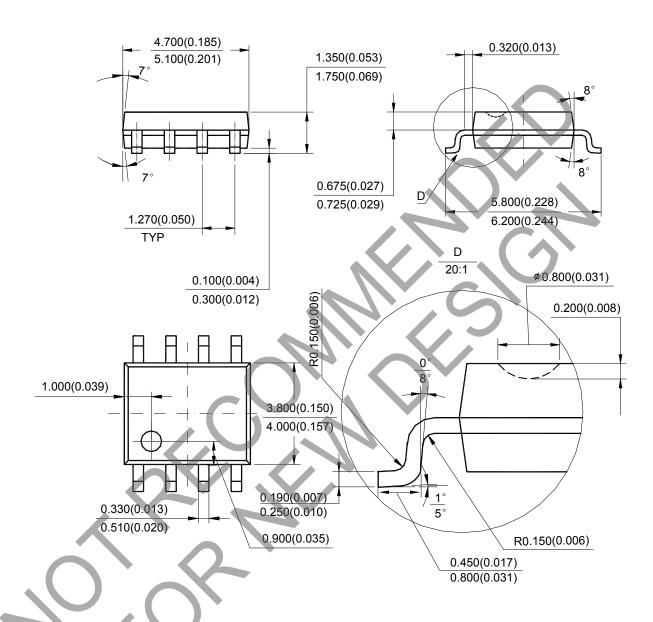
Package	Temperature Range	Part Number	Marking ID	Packing
SOIC-8	-40 to +85°C	AP3502EM-G1	3502EM-G1	Tube
		AP3502EMTR-G1	3502EM-G1	Tape and Reel



Package Outline Dimensions (All dimensions in mm(inch).)

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SOIC-8



Note: Eject hole, oriented hole and mold mark is optional.



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